

10-18-02

2827

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Yoshiyuki UCHINONO et al.

Docket No.

11411.002001

Serial No.
09/995,085Filing Date
November 27, 2001Examiner
Dinh, Tuan T.Group Art Unit
2827

Invention: MULTILAYER CIRCUIT BOARD AND METHOD OF MANUFACTURING THE SAME

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	7 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	1 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0591
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- ☐ Any additional filing fees required under 37 C.F.R. 1.16.
- ☒ Any patent application processing fees under 37 CFR 1.17.

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Dated: 10/17/02

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I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

Lisa H. Smith

Typed or Printed Name of Person Mailing Correspondence

CC:

CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)Applicant(s): **Yoshiyuki UCHINONO et al.**

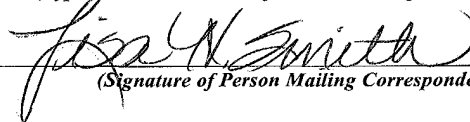
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2827Invention: **MULTILAYER CIRCUIT BOARD AND METHOD OF MANUFACTURING THE SAME**

I hereby certify that the following correspondence:

Reply Under 37 CFR 1.111*(Identify type of correspondence)*

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October 17, 2002*(Date)***Lisa H. Smith***(Typed or Printed Name of Person Mailing Correspondence)**(Signature of Person Mailing Correspondence)***EV 178455665 US***("Express Mail" Mailing Label Number)***Note: Each paper must have its own certificate of mailing.**



ATTORNEY DOCKET NO.: 11411.002001

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Yoshiyuki UCHINONO et al.
Serial No.: 09/995,085
Filed : November 27, 2001
Title : MULTILAYER CIRCUIT BOARD AND METHOD OF MANUFACTURING
THE SAME

Art Unit : 2827
Examiner : T. Dinh

Assistant Commissioner for Patents
Washington, DC 20231

REPLY UNDER 37 CFR § 1.111

In response to the Office Action dated July 18, 2002, please amend the application as follows and consider the included remarks.

IN THE CLAIMS:

Please amend claim 1 as follows. A marked-up version of the amended claim is attached.

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1. (Amended) A multilayer circuit board, comprising:

B' a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;

a multilayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit pattern and an insulation layer formed on said conductive layer by film formation;

a second conductive layer formed on the second surface of said substrate, by which said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers.